MOSFETs Silicon N-channel MOS (U-MOS ₩-H)

# TPH11006NL

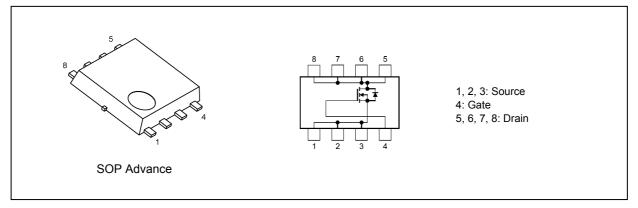
#### 1. Applications

- Switching Voltage Regulators
- DC-DC Converters
- Motor Drivers

#### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 6.4 \text{ nC}$  (typ.)
- (3) Low drain-source on-resistance:  $R_{DS(ON)} = 9.6 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 10 \text{ V})$
- (4) Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 60 \ V)$
- (5) Enhancement mode:  $V_{th}$  = 1.5 to 2.5 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.2 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \degree$ C unless otherwise specified)

Characterist	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	60	V
Gate-source voltage			V <sub>GSS</sub>	±20	]
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I <sub>D</sub>	40	A
Drain current (DC)	(T <sub>c</sub> = 25 °C)	(Note 1)	I <sub>D</sub>	17	]
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I <sub>DP</sub>	81	1
Power dissipation	(T <sub>c</sub> = 25 °C)		PD	34	W
Power dissipation	(t = 10 s)	(Note 3)	PD	2.8	]
Power dissipation	(t = 10 s)	(Note 4)	PD	1.6	1
Single-pulse avalanche energy		(Note 5)	E <sub>AS</sub>	33	mJ
Avalanche current			I <sub>AR</sub>	17	A
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	]

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

#### 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Channel-to-case thermal resistance	(T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	3.67	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	44.6	
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 4)	R <sub>th(ch-a)</sub>	78.1	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Limited by silicon chip capability.

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5:  $V_{DD}$  = 48 V,  $T_{ch}$  = 25 °C (initial), L = 89  $\mu$ H, I<sub>AR</sub> = 17 A



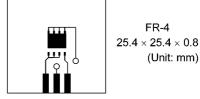


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a) Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

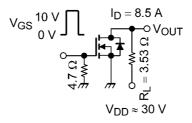
#### 6. Electrical Characteristics

#### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V	_		±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_		10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60		_	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	45	_	_	1
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.2 mA	1.5		2.5	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 8.5 A	_	12.8	17	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8.5 A	_	9.6	11.4	

#### 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1500	2000	pF
Reverse transfer capacitance	C <sub>rss</sub>			23	50	
Output capacitance	C <sub>oss</sub>	]		350	_	
Gate resistance	r <sub>g</sub>	—		0.6	1.1	Ω
Switching time (rise time)	tr	See Fig. 6.2.1		4.0	_	ns
Switching time (turn-on time)	t <sub>on</sub>			11.0	_	
Switching time (fall time)	t <sub>f</sub>	]		7.1	_	
Switching time (turn-off time)	t <sub>off</sub>	]		27	_	]



 $Duty \le 1\%, \ t_w = 10 \ \mu s$  Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics ( $T_a = 25$ °C unless otherwise specified)

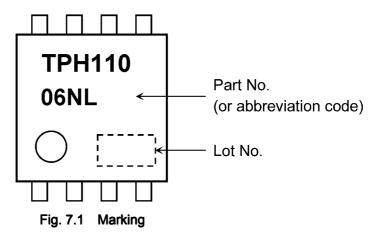
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD}\approx 30$ V, $V_{GS}$ = 10 V, $I_{D}$ = 17 A	_	23	_	nC
gate-drain)		$V_{DD} \approx 30$ V, $V_{GS}$ = 4.5 V, $I_D$ = 17 A	_	11.2	—	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 30$ V, $V_{GS}$ = 10 V, $I_D$ = 17 A		5.0	_	
Gate-drain charge	Q <sub>gd</sub>		_	4.1	_	
Gate switch charge	Q <sub>SW</sub>		_	6.4	_	

#### 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

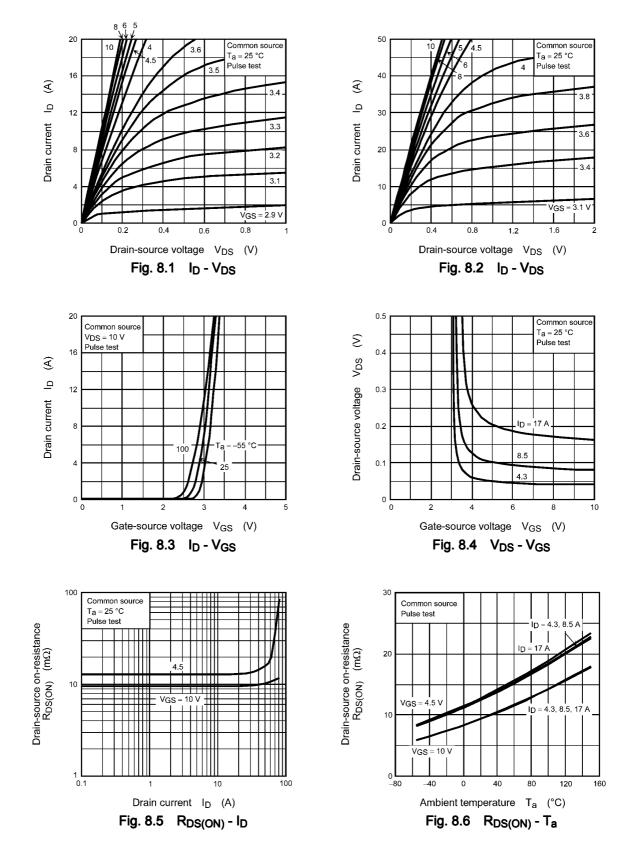
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 6)	I <sub>DRP</sub>	—	_	_	81	А
Diode forward voltage		$V_{DSF}$	I <sub>DR</sub> = 17 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

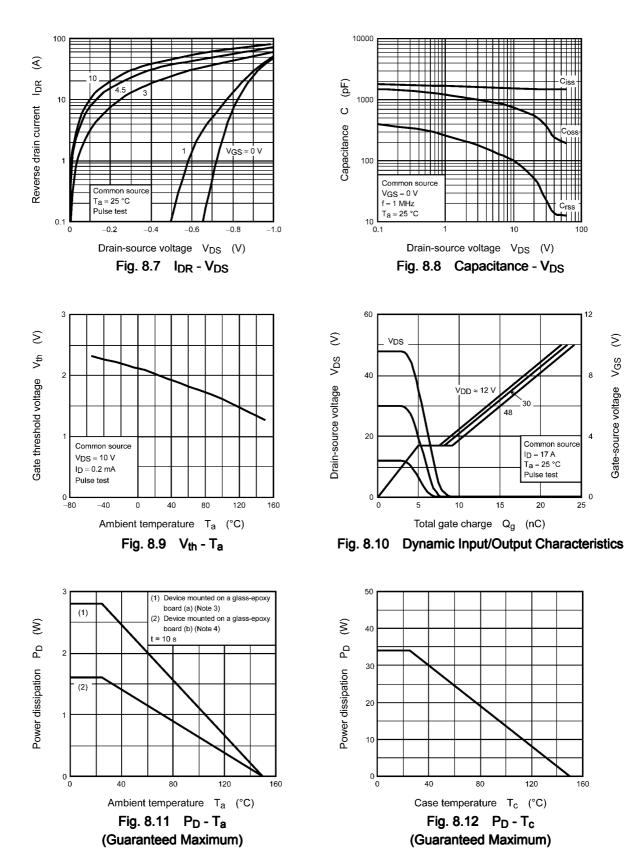
Note 6: Ensure that the channel temperature does not exceed 150 °C.

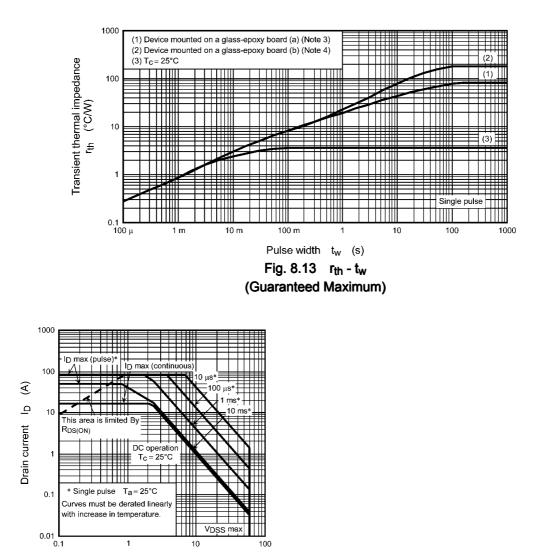
7. Marking



#### 8. Characteristics Curves (Note)







Note: The above characteristics curves are presented for reference only and not guaranteed by production test,

100

1

unless otherwise noted.

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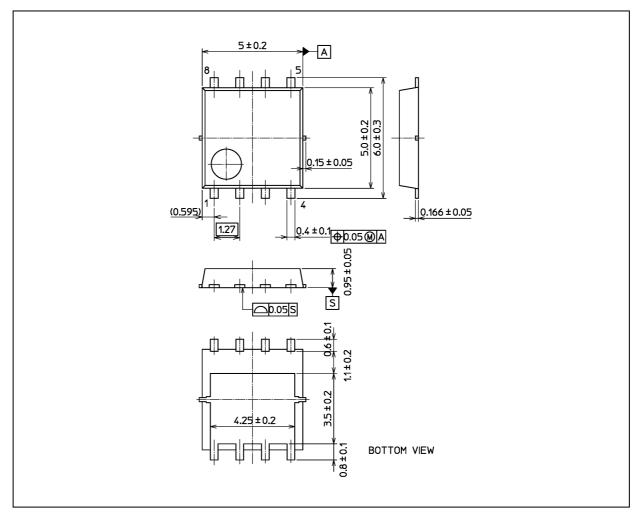
Drain-source voltage V<sub>DS</sub> (V) Fig. 8.14 Safe Operating Area (Guaranteed Maximum)



#### **TPH11006NL**

#### **Package Dimensions**

Unit: mm



Weight: 0.069 g (typ.)

TOSHIBA: 2-5Q1S

Nickname: SOP Advance

Package Name(s)

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